

MEC1 SERIES

(1.00 mm) .0394"

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

- Insulator Material:**
Black LCP
- Contact Material:**
BeCu
- Plating:**
Sn or Au over 50 μ" (1.27 μm) Ni
- Operating Temp Range:**
-55 °C to +125 °C
- Current Rating:**
2.2 A per pin (2 adjacent pins powered)
- Voltage Rating:**
300 VAC
- Insertion Depth:**
(5.84 mm) .230" to (8.13 mm) .320"
- RoHS Compliant:**
Yes

PROCESSING

- Lead-Free Solderable:**
Yes
- SMT Lead Coplanarity:**
(0.10 mm) .004" max (05-20)
(0.15 mm) .006" max (30-70)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



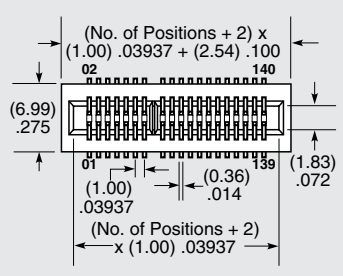
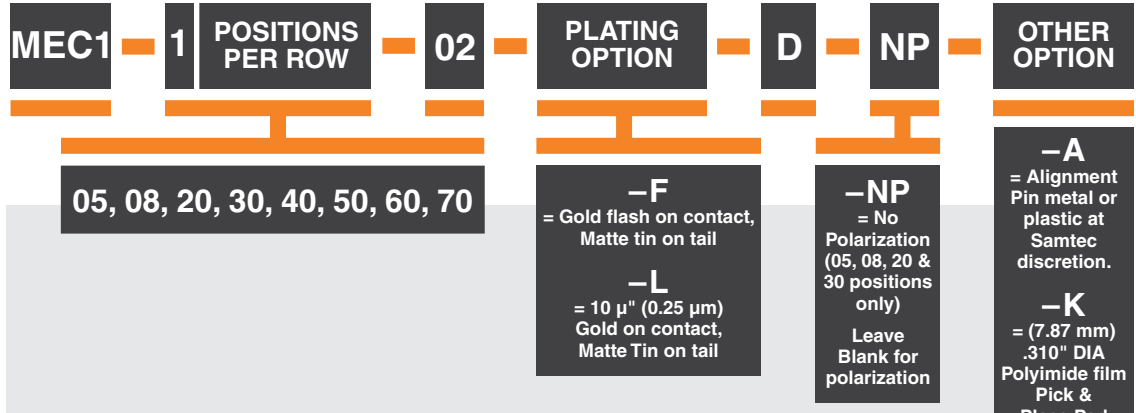
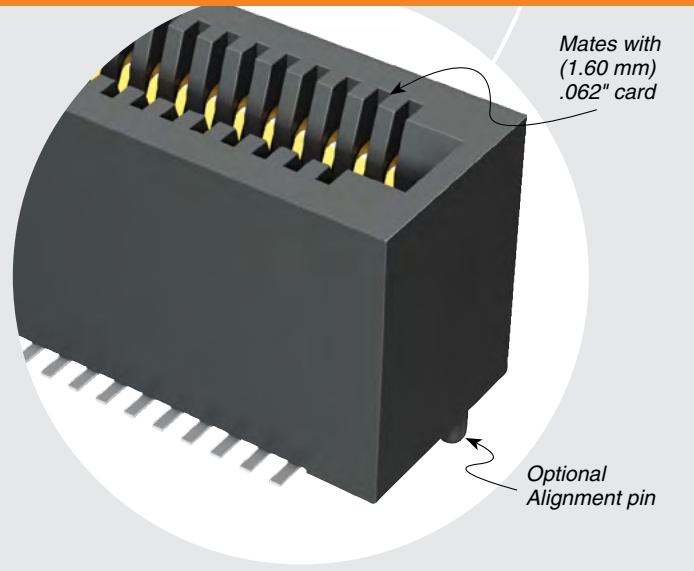
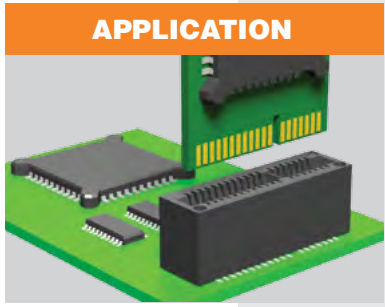
ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
 - Other platings
- Contact Samtec.

Important Note:
Samtec recommends that pads on the mating board be Gold plated.

Notes:
While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.
Some sizes, styles and options are non-standard, non-returnable.

Mates with:
(1.60 mm) .062" card



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

